Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	2 X 2 X 0.55 (1.5 X 1.0 EP)
Lead Count	8
Terminal Finish	NiPdAu
MS Number	MS012249A

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.07E-03	84.50	845000	34.98	349810
Thermosets	Epoxy & Phenol resin	Proprietary	9.00E-04	15.00	150000	6.21	62096
Other inorganic materials	Carbon black	1333-86-4	3.00E-05	0.50	5000	0.21	2070
Subtotal			6.00E-03	100.00	1000000	41.40	413976

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	5.32 E-03	97.50	975000	36.73	367294
Copper & its alloys	Iron	7439-89-6	1.28 E-04	2.35	23500	0.89	8853
Copper & its alloys	Zinc	7440-66-6	6.55 E-06	0.12	1200	0.05	452
Copper & its alloys	Phosphorus	7723-14-0	1.64 E-06	0.03	300	0.01	113
Subtotal			5.46 E-03	100.00	1000000	37.67	376712

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	2.97 E-04	95.02	950185	2.05	20512
Precious metals	Palladium	7440-05-3	1.27 E-05	4.06	40590	0.09	876
Precious metals	Gold	7440-57-5	2.89 E-06	0.92	9225	0.020	199
Subtotal			3.13 E-04	100.00	1000000	2.16	21588

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	7.07 E-05	99.00	990000	0.49	4875
Precious metals	Palladium	7440-05-3	7.14 E-07	1.00	10000	0.005	49
Subtotal			7.14 E-05	100.0	1000000	0.49	4924

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.57 E-03	100.0	1000000	17.73	177305

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.13 E-05	77.00	770000	0.42	4231
Other organic materials	Acrylic resin	Proprietary	5.57 E-06	7.00	70000	0.04	385
Other organic materials	Acrylate	Proprietary	4.38 E-06	5.50	55000	0.03	302
Other organic materials	Polybutadiene derivative	Proprietary	3.58 E-06	4.50	45000	0.02	247
Thermoset	Epoxy resin	Proprietary	1.99 E-06	2.50	25000	0.01	137
Other organic materials	Butadiene Copolymer	Proprietary	1.19 E-06	1.50	15000	0.01	82
Others	Additive	Proprietary	1.19 E-06	1.50	15000	0.01	82
Others	Peroxide	Proprietary	3.98 E-07	0.50	5000	0.003	27
Subtotal			7.96 E-05	100.0	1000000	0.55	5495

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.45 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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